

GP 1746



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: 98 P7501 US

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TC 1700 MAIL ROOM

In re the application of:)
Ramachandran et al.) Group Art: 1746
Serial No.: 09/204,706) Examiner: A. Olsen
Filing Date: December 3, 1998)
Title: REMOVAL OF POST-RIE POLYMER)
ON Al/Cu METAL LINE)

AMENDMENT UNDER 37 C.F.R. §1.115

Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed April 11, 2001,
which rejected the claims in the above-identified patent
application, applicants respectfully request reconsideration,
based upon the amendments hereinafter set forth

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IN THE CLAIMS:

13. (Amended) In a metal etch tool for removing post-RIE
polymer rails formed on a Al/Cu metal line of semiconductor
structure, the improvement comprising: an integrated metal
etch tool comprising [a] separate chamber means for
forming a water-only plasma process to strip the photo-
resist layer of a semiconductor [or micro-electronic]
composite structure previously subjected to a RIE process; and
separate chamber means for

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